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**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2822

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF  
MANUFACTURING THE PACKAGE

**PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of two months, extending the time for responding to the Office Action of September 20, 2005 to December 20, 2005.

A check for the statutory fee of \$450.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

12/21/2005 HALI11 00000123 10721382

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450.00 DP

Respectfully submitted,

Handwritten signature of Alan J. Kasper.

Alan J. Kasper

Registration No. 25,426

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**23373**

CUSTOMER NUMBER

Date: December 20, 2005